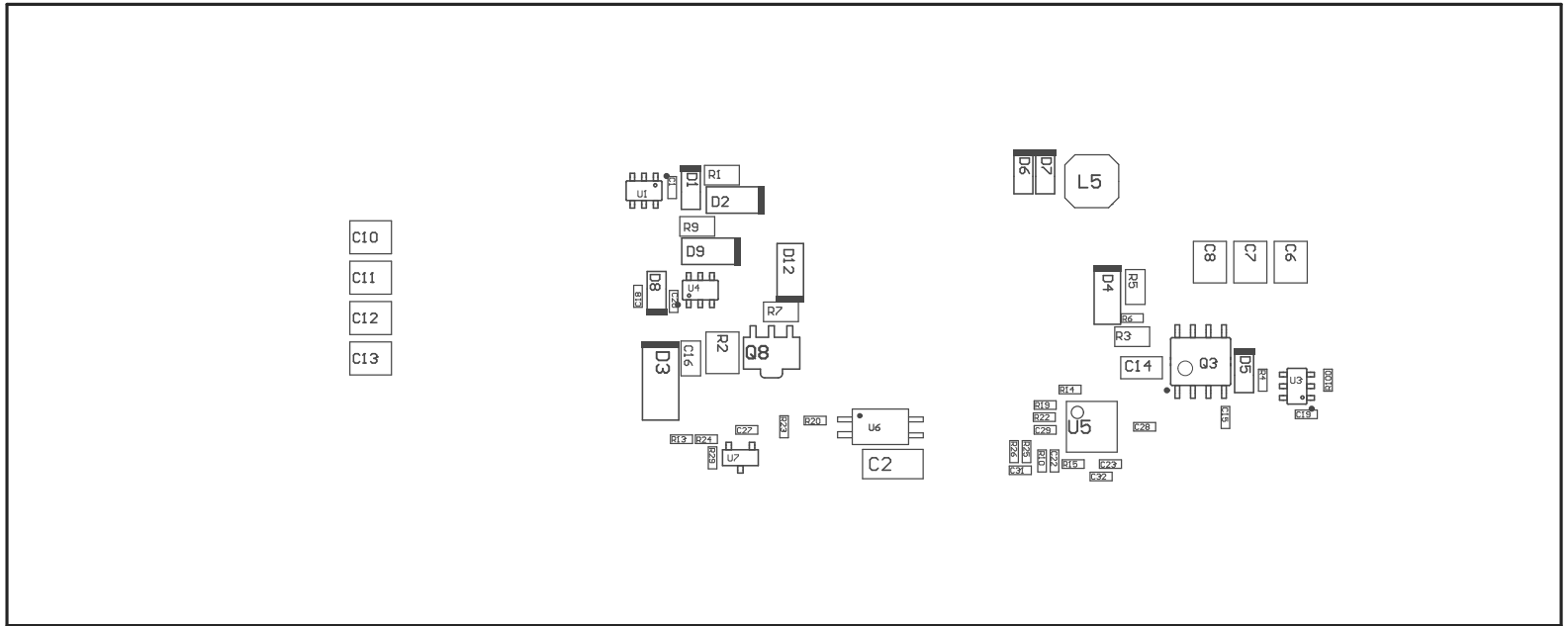


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP9656	REV: B	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 10/13/2017 12:22:55 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP9656	REV: B	SUN REV: Not In VersionControl
	IGNORE -> Bottom Overlay		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/13/2017 12:22:56 PM	TEXAS INSTRUMENTS	

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